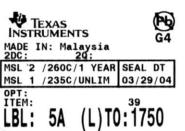
PCN Number:		201	20170504000							P	CN Date:	May 8 2017		
Title		on of TI Chengdu BUMP (CBUMP) as an Additional Bump and TI Chengdu A/T an Assembly site for the BQ25898CYFFR/T												
Customer Contact:		PCN A	PCN Manager D				ept:	Quality Services						
	osed	1 st Ship		Aug 8 2017				Estima	tan Samnia Avallanility:			Provided upo Request	n	
	nge Ty	pe:						Request			Trequest			
		mbly Site		Assembly P				rocess			Assembly Materials		Materials	
Ħ	Desic			Electrical S			_				Mechanical Specification			
	Test							ipping/Labeling			Test Process			
\boxtimes	Wafe	r Bump Si	te		Wafer Bump Material				ıl		Wafer Bump Process			
		r Fab Site			Wafer Fab Materials							Wafer Fal	Process	
						Part nun	nbe	er change						
							PC	N Deta	ails					
Desc	criptio	n of Chai	nge:											
Texas Instruments is pleased to announce the qualification of TI Chengdu BUMP (CBUMP) as an Additional Bump and TI Chengdu A/T (CDAT) as an additional Assembly site for the BQ25898CYFFR/T. There is no construction differences in devices built between the various sites.							•							
Reas	son fo	r Change	:											
Cont	inuity	of Supply												
Anti	cipate	d impact	on Fi	n Fit, Form, Function, Quality or Reliability (positive / negative):										
None	9													
Anti	cipate	d impact	on M	late	ria	l Declara	tio	n						
No Impact to the Material Declaration				Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <u>TI ECO website</u> .										
Chai	nges t	o produc	t iden	ntifi	cat	ion resul	ltin	g from t	this PCN:					
												1		_
	Assemb	oly Site	Assen	nbly	Site	e Origin (22	2L)	Assembl	y Country Code	(21	LL)	Ass	embly City	
TI Clark			QAB					PHL			Angeles	City, Pampanga		
CDAT			CDA				CHN				Chengdu			



5A



(1P) SN74LS07NSR (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483SI2 (P) (2P) REV: (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MVC 23L) ACO: MYS

Topside Device marking (if included):

Assembly site code for QAB= I

Assembly site code for CDA = 8



TI Information Selective Disclosure

Qualification Plan

Chengdu BUMP (CBUMP) start -up for BOPCOA - (BQ25898CYFFR)

Product Attributes

Attributes	Qual Device: BQ25898CYFFR
Assembly Site	CHENGDU A/T
Package Family	WCSP
Flammability Rating	UL 94 V-0
Wafer Fab Supplier	RFAB
Wafer Fab Process	LBC7

⁻ QBS: Qual By Similarity

Qualification Results expected 07-07-2017

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: BQ25898CYFFR
BLR	BLR - Drop test	30 times	3/24/TBD
BLR	BLR - Temp Cycle, -40C / +125C	1000 Cycles	3/108/TBD
ED	Electrical Characterization, side by side	Per Datasheet Parameters	TBD
HBM	ESD HBM	2000V	3/9/TBD
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/TBD
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	TBD
MQ	Manufacturability (Bump)	(per mfg. Site specification)	TBD
PD	Physical Dimensions	(per mechanical drawing)	3/15/TBD
SBS	Bump-shear	unstressed	3/150/TBD
TC	T/C -55C/125C	700 Cycles	3/231/TBD
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	3/231/TBD

- Preconditioning was performed for Autodave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

⁻ Qual Device BQ25898CYFFR is qualified at LEVEL1-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com